

8 K × 8 / 3.3 Volts High Speed CMOS SRAM

Short description. Please refer to the full datasheet available on TEMIC web for detailed technical information.

Description

The L 65764 is a high speed CMOS static RAM organized as 8192 × 8 bits. It is manufactured using TEMIC high performance CMOS technology.

Access times as fast as 25 ns are available with maximum power consumption of only 216 mW.

The L 65764 features fully static operation requiring no external clocks or timing strobes. The automatic power-down feature reduces the power consumption by 73 % when the circuit is deselected.

Easy memory expansion is provided by active low chip select ($\overline{CS1}$), an active high chip select (CS2), an active low output enable (\overline{OE}) and three state drivers.

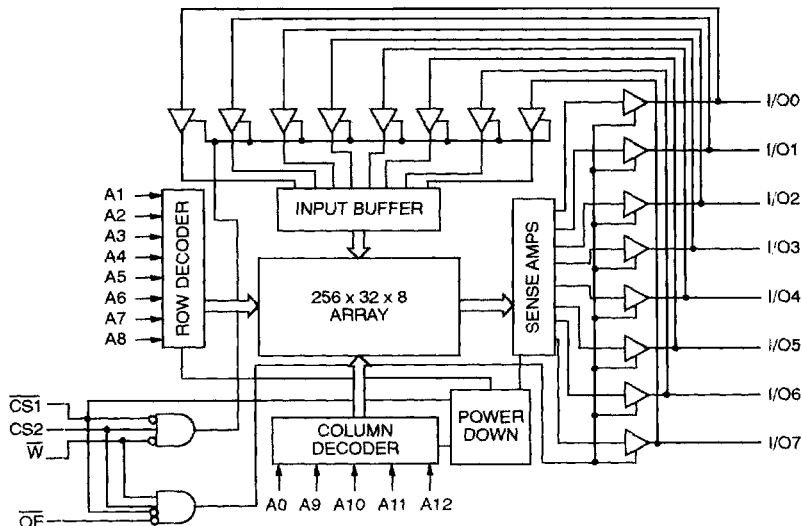
L 65764 provides fast access time with 3,3 volts power supply, perfectly designed for portable applications (PC cache memory... etc).

Features

- Single supply 3.3 V ± 0.3 V
- Fast access time
Commercial : 25/35/45/55 ns (max)
Military : 35/45/55 ns (max)
- Low power consumption
Active : 216 mW (typ)
Standby : 36 mW (typ)
- 300 and 600 mils width package
- Asynchronous
- Capable of withstanding greater than 2000 V electrostatic discharge

Interface

Block Diagram



Ordering Information

TEMPERATURE	PACKAGE	DEVICE TYPE	GRADE	FLOW	
C	L	UI	65764	- 25	: RD
C : Commercial M : Military	0 - Chip form 1P - Ceramic 28 pins 300 mils 1E - Ceramic 28 pins 600 mils 4 - LCC 32 pins 3P - Plastic 28 pins 300 mils 3I - Plastic 28 pins 600 mils TI - SOIC 28 pins 300 mils TP - SOIC 28 pins 330 mils UI - SOJ 28 pins	8 k x 8 high speed static RAM	- 25 = 25 ns - 35 = 35 ns - 45 = 45 ns - 55 = 55 ns	R : Tape & Reel option RD : Tape & Reel/Dry pack	

Military Version

The following table gives package/access time/process flow available combinations

Temp range	Package	Access Time (ns)			Mil flows
		35 (K)	45 (M)	55 (N)	
M	1	X	X	X	X
	1E	X	X	X	X
	4	X	X	X	X
	0	X	X	X	X

X = call sales office for availability

The information contained herein is subject to change without notice. No responsibility is assumed by TEMIC for using this publication and/or circuits described herein : nor for any possible infringements of patents or other rights of third parties which may result from its use.